TO.: MINDA NO.: M201124



APPROVAL SHEET

MULTILAYER CERAMIC CAPACITOR
Commercial Grade
(High Voltage Type (100V~3000V))
(IEC-60384 Qualified)

Approved by customer : (signing or stamping here)									

SAMWHA CAPACITOR CO., LTD.							
Writtern by							
21-85	gros-	7/-					

2020. 11. 24.



Address : 124, BUK-RI, NAMSA-MYUN YOUNGIN-SI, KYUNGKI-DO, KOREA

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Home page: www.samwha.com

< SPEC SUMMARY >										
SAMWHA Part no.		CS3	225X7R225K101NRK							
Type		High voltage								
Item	Specification	Unit	Test methods and Conditions(Capacitance,IR)							
Capacitance	2.2	μF								
Capacitance Tolerance	± 10	%	Testing Frequency: 1 ±0.2kHz Testing Voltage: 1 ±0.2Vrms							
Dissipation Factor	Max. 5	%	Testing voitage . 1 ±0.2 viiiis							
Insulation Resistance	More than 45.4	MΩ	Applied the rated voltage for 2 minutes of charging.							
	3.20 ±0.40	L (mm)	*Capacitance Tolerance Code page 1/9							
Chip Size	2.50 ±0.25	W (mm)	*Chip size page 2/9							
	2.00 ±0.25	T (mm)	*Characteristics & Test Method page 3/9~6/9							

Enactment :	STANDARD	NO	SW - M - 04B	
March 27,1996	MULTILAYER CERAMIC CAPACITOR	Dogo	1 / 9	
,	Commercial Grade	Page		

1. General Article

Application Range

These specifications refer to the "Multilayer Ceramic Capacitors "mainly used to the computer equipment, communication equipment.

*Caution: Industrial equipment / For the high reliability equipment / LED equipment / Etc.

Please contact sales representatives or product engineers before using the products.

(For details, please refer Page 9)

2. General Code

(1) Type Designation

<u>CS</u>	<u>3225</u>	<u>X7R</u>	<u>225</u>	<u>K</u>	<u>101</u>	<u>N</u>	<u>R</u>	K
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

- 1) Multilayer Ceramic Capacitor (Commercial Grade)
- 2) Size Code:

This is expressed in tens of a millimeter.

The first two digits are the length, The last two digits are width.

3) Temperature Coefficient Code

Classification	Code	Temperature Range	Capacitance Tolerance
Class I	C0G	-55 to +125℃	±30 ppm/℃
	X5R	-55 to +85℃	±15%
Class II	X7R	-55 to +125℃	±15%
	Y5V	-30 to +85℃	+22% ~ -82%

4) Capacitance Code(Pico farads):

The nominal Capacitance Value in pF is expressed by three digit numbers.

The first two digits represents significant figures and the last digit denotes the number of zero ex) 104 = 100000 pF

R denotes decimal

8R2 = 8.2 pF

5) Capacitance Tolerance Code

Code	Tolerance
В	± 0.1 pF
С	± 0.25 pF
D	± 0.5 pF
F	± 1.0 %
G	± 2.0 %
J	± 5 %
K	± 10 %

Code	Tolerance
М	± 20 %
Р	+ 100, -0%
Z	+ 80, -20%
Н	+ 0.25/-0 pF
I	+ 0/-0.25 pF
U	+ 5/-0 %
V	+ 0/-5 %

6) Voltage Code

code	6R3	100	160	250	350	500	101	201	251	501	631	102	202	302
Val	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC	DC
Vol.	6.3V	10V	16V	25V	35V	50V	100V	200V	250V	500V	630V	1KV	2KV	3KV

7) Termination Code

ex) N: Ni-Sn (Nickel-Tin Plate)

A: Ag/Ni-Sn (Ag Epoxy/Nickel-Tin Plate) -> Soft Termination Type

8) Packing Code

ex) R: 7" Reel Type L: 13" Reel Type B: Bulk Type

9) Thickness option

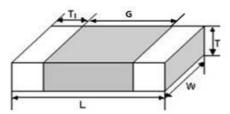
Thickness(mm)		Code	Thickne	Code	
t	Tol(±)	Oode	t	Tol(±)	Oode
0.30	0.03	Blank	1.30	0.20	Е
0.50	0.05	Blank	1.35	0.20	Н
0.60	0.10	А	1.60	0.20	1
0.80	0.10	В	1.80	0.20	J
0.85	0.15	В	2.00	0.25	K
1.00	0.15	Е	2.50	0.25	L
1.10	0.15	Е	2.80	0.30	М
1.15	0.15	Е	3.20	0.30	N
1.25	0.15	Е	5.00	0.40	0

3. Temperature Characteristics

See Page 3/9 (No.7)

4. Constructions and Dimensions

(I) Dimensions



(Unit: mm)

	Dimension									
Code	Ler	igth	Wi	dth	T1(min)	G(min)				
	L	Tol(±)	W	Tol(±)	1 1 (111111)	G(IIIIII)				
0603	0.60	0.03	0.30	0.03	0.05	0.15				
1005	1.00	0.05	0.50	0.05	0.05	0.30				
1608	1.60	0.15	0.80	0.10	0.10	0.50				
2012	2.00	0.20	1.25	0.15	0.10	0.65				
3216	3.20	0.30	1.60	0.20	0.15	1.00				
3225	3.20	0.40	2.50	0.25	0.15	1.05				
4520	4.50	0.40	2.00	0.25	0.20	1.50				
4532	4.50	0.40	3.20	0.30	0.20	1.50				
5750	5.70	0.50	5.00	0.40	0.30	1.85				

(2) Construction of Termination



Specifications and Test Methods (High voltage type)

		Spe	cification					
No.	Item	Class I	Class II		Test Me	thods	and Conditions	S
1	Operating Temperature Range	C0G :-55 to+125°C	X7R : −55 to +125°C					
2	Dimensions	Within the specified dimen	sion	Using	calipers			
3	Voltage proof	I			o failure should be observed when voltage in table tween the terminations, provided the charge/discless than 50mA. Cap. Rated voltage Test voltage DC100V~630V 150% of the rated voltage DC1kV, DC2kV DC3kV, DC3.15kV 120% of the rated voltage DC100V~630V 150% of the rated voltage DC10V 630V 150% of the rated voltage DC1kV DC2kV DC3kV 120% of the rated voltage			Time e a 1to5 sec.
4	Insulation Resistance	More than 10,000 MΩ	-DC100V~1KV :C≥0.01µF:More than 100M\\(\rho_\mu F\) :C<0.01µF:More than 10,000M\(\rho_\mu C2~3KV:More than6,000 M\)	Rated voltage ≥DC500V: The insulation resistance sho				tance should
5	Capacitance	within the s	pecified tolerance	Cap	Testing freq	uency	Testing Voltage	Measure temperature
6	Dissipation Factor	COG Char.: 30pFmin : Q≥1,000(DF≤0.1%) 30pFmax : Q≥400+20C (DF≤1/ (400+20C))	5% max	Performaccor • Meas Take	1±0.1₩(C≥ R 1±0.2k measurement rm the initial m ding to Note1 urement after t it out and set	easurer for Clasest it for 2	ss II 24±2 hours (Class	25°C
7	Temperature characteristic of capacitance	Temp. Coefficient C0G char.: 0±30ppm/°C (Temp. Range: -55to+125°C)	Cap. Change within ±15% (Temp. Range: -55 to +125℃)	COG: The temperature coefficient is determined using capacitance measured in step 3 as a reference. When cycling the temperature sequentially from step 1 through 5 the capacitance should be within the specific tolerance for the temperature coefficient. Step			step 1 specified red with the	

			Specifi	cation				
No.	l1	tem	Class I	Class II	Test Methods and Conditions			
8	8 Adhesive Strength of Termination		No removal of the terminations or other defect should occur		Solder the capacitor to the testing jig(glass epoxy board) shown in Fig. 1 using a eutectic solder. Then apply 10N force in the direction of the arrow. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. 10N(5N:Size 1.6×0.8mm only), 10±1s Speed: 1.0mm/s Glass Epoxy Board			
		Appearance	No defects or abnormalities	3				
		Capacitance	Within the specified tolerance		The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency			
9	9 Vibration COG Char.: 30pFmin O >1 000(DE<0.1%) being varied and 55Hz. The to 10Hz, sho motion should		being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 min. This motion should be applied for a period of 2hrs. in each 3mutually perpendicular directions(total of 6hrs.)					
10	Substrate bending test		(mm) a 1.6×0.8 1.0 3 2.0×1.25 1.2 4 3.2×1.6 2.2 5 3.2×2.5 2.2 5 4.5×2.0 3.5 7	00ccur. 44.5 1:1.6 mension(mm) b	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 2 using a eutectic solder. Then apply a force in the direction shown in Fig. 3. The soldering should be done either with an iron or using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. **Test condition** - Bending limit : 1mm - Pressurizing speed : 1mm/sec - Holding time : 5±1sec			
11	11 Solderability		95% of the terminations is and continuously.	to be soldered evenly	Immerse the capacitor in a solution of ethanol and rosin(25% rosin in weight proportion). Immerse in eutectic solder solution for 2±0.5 sec. at 245±5°C. Immersing speed: 25±2.5mm/s			

	. Item		Spe								
No.			Class I	Class II	Test Methods and Condition						
		Appearance	No defects which may	affect performance	Preheat the capacitor at 120 to 150°C						
		Capacitance	within ±2.5%or ±0.25pF	within ±10%	Immerse the capacitor in eutectic solder s 260±5℃ for 10±1 sec.				on at		
		change	(whichever is larger) COG Char.:	2001361	OI TO±1 Sec	J.					
			30 _p Fmin			g speed:2	5±2.5mm	n/s			
		Dissipation	: Q≥1,000(DF≤0.1%)		Initial mea						
4.0	Resistance	Factor	30 _p Fmax	5% max		the initial g to Note1					
12	to Soldering Heat	(or Q)	: Q≥400+20C			ent after te		.55 11			
	i ieat		(DF≦1/ (400+20C))		Let sit at r	oom Tempe	rature for	,			
				-DC100V~1KV		Class I), 2 g for more		Class II) then r	measure.		
		I.R.	More than 10,000MΩ	:C≥0.01 µF:More than 100MQ·µF	Step		mperature	Time			
				:C<0.01 μ F:More than 10,000M Ω	1	100	℃ to 120℃		n		
				-DC2~3KV:More than1,000 MΩ	2	170	℃ to 200℃	C 1 min	n		
		Appearance	No defects which may	affect performance	I .			to the 4 heat tr	eatments		
		Capacitance Change	Within ±2.5%or ±0.25pF (whichever is larger)	within ±15%	listed in the	e following	table.				
		Change	COG Char.:		Step	1	2	3	4		
			30 _p Fmin			. operating emp. ±3	Room Temp	Max. operating temp. ±2	Room Temp		
	Rapid change of	d Dissipation ; Q≥1,000(DF≦	: Q≥1,000(DF≤0.1%)		(°C) to	30±3	2 to3	30±3	2 to3		
13			30 _p Fmax	5% max	(min)	30±3	2 100	30±3	2 103		
	temperature	erature : Q≥400+20C			Initial measurement						
			(DF≦1/ (400+20C))		Perform the initial measurement according to Note1 for Class II Measurement after test Perform the final measurement according to Note2						
		I.R	More than 10,000MΩ	-DC100V~1KV :C≥0.01 μF:More than 100MΩ·μF :C<0.01 μF:More than 10.000MΩ							
				-DC2~3KV:More than 3,000MΩ							
		Appearance	No defects which may	and relative hur	midity of						
		Capacitance	within ±5% or ±0.5pF	Within ±15%	Let the capacitor sit at 40±2°C and relative humidity of 90 to 95% for 500+24/-0 hrs.						
		Dissipation C>30pE	(Whichever is larger)								
14	Damp heat,		C \leq 30pF : Q \geq 350 C \leq 30pF : Q \geq 275+ $\frac{5}{2}$ /C	7.5% max	Initial measurement Perform the initial measurement according to Note1 for Class II						
' -	steady state										
		I.R	-DC100V~1KV	·Measurement after test							
			More than 1,000MΩ	:C≥0.01 μF:More than 10MΩ·μF :C<0.01 μF:More than 1.000MΩ	Perform the final measurement according						
				-DC2~3KV:More than 1,000MQ			to Note2				
		Appearance	No defects which may	affect performance	I .	voltage in f	ollowing t	able			
		Capacitance	within $\pm 3\%$ or ± 0.3 pF	DC100V,630V:Within ±15%	-for 1,000+48/-0hrs. at maximum operating temperature ±3°C.						
		Change	(Whichever is larger)	DC1KV:Within ±20%							
		Onlange	(111110101110110110110110110110110110110	DC2~3KV:Within ±20%	The charge	e/discharge 	current is	less than 50m.	A.		
		Dississation	COG Char. :		Operating temperature	e Rated vo	Itage	Test voltage			
		Dissipation	C≥30pF : Q≥350 5,	7.5% max	range	Rated volta	nge.				
		(or Q) C<30p	C<30pF : Q \ge 275+ $\frac{5}{2}$ /C		COG	≥DC1KV	Hai	ed voltage			
15	Endurance					Rated volta <dc1kv< td=""><td>120</td><td>0% of the rated v</td><td>oltage</td></dc1kv<>	120	0% of the rated v	oltage		
		urance			X7R	DC100V~2 DC500V~6		0% of the rated v			
					\ \^\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	DC1KV~DC		% of the rated v			
				-DC100V~1KV :C≥0.01μF:More than 10MΩ·μF			,				
		I.R.	More than 1,000MΩ	$C<0.01\mu$ F:More than $1,000M\Omega$		asurem ent	l m ·	omont	ina		
				-DC2~3KV:More than 2,000MΩ	Perform the initial measurement according						
					to Note1 for Class II Measurement after test						
					Perform the final measurement according						
					to Note	2					

			S	pecification				
No.	 	tem	Class I	Class II	Test Methods and Conditions			
	Humidity Load	Appearance		No defects which may affect performance	Apply the rated voltage at 40±2°C and relative			
		Capacitance Change		Within ±15%	humidity of 90 to 95 for 500+24/-0 hrs. Initial measurement			
16	(Application : DC250V	Dissipation (or Q)		7.5% max	Perform the initial measurement according to Note1 for Class II -Measurement after test			
	item)	I.R.		C≥0.01 μ F:More than 10M Ω : μ F C<0.01 μ F:More than 1,000M Ω	Perform the final measurement according to Note2			

*Note1. Initial Measurement for Class II

Perform a heat treatment at 150+0,-10℃ for one hour and then let sit for 24±2 hours at room temperature, then measure

- *Note2. Measurement after test
 - 1.Class I

Let sit for 24±2 hours at room temperature, then measurement

2.Class II

Perform a heat treatment at 150+0,-10℃ for one hour and then let sit for 24±2 hours at room temperature, then measure.

"Following the International standards, the title of each test item is subject to change."

5. Packing

- (1) Bulk packing
 - 1 1000 pcs per Polybag
 - 2 5 Polybags per Inner box
 - 3 10 Inner boxes per Out box
- (2) Reel Packing
 - ① 8~10 Reels per Inner box
 - 2 6 Inner boxes per Out box
- (3) Reel Dimensions



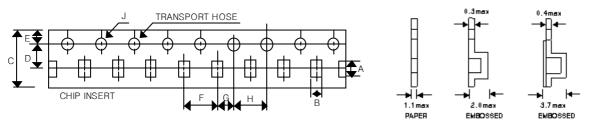


						(L	Jnit: mm)
MARK	SIZE	Α	В	С	D	E	W
7 " REEL	0603~3225	Φ178±2	Ф50Min	Ф13±0.5	Φ21±0.8	2±0.5	10±1.5
/ REEL	4520~4532	Ф180+0,-3	Ф60-0,+1	Φ13±0.2	Ф57-0+1	3±0.2	13±0.5
13 " REEL	1005~3225	Ф330±2	Φ70Min	Ф13±0.5	Φ21±0.8	2±0.5	10±1.5

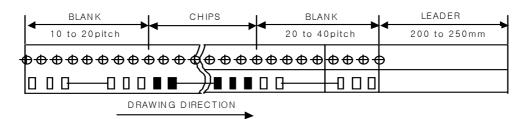
(4) Number of Package

TYPF	EIA CODE	7"	13"		
ITE	EIA CODE	Qt/REEL	Qt/REEL		
CS0603	CC0201	15,000			
CS1005	CC0402	10,000	50,000		
CS1608	CC0603	4,000	15,000		
CS2012	CC0805	3,000 ~ 4,000	8,000 ~ 15,000		
CS3216	CC1206	2,000 ~ 4,000	6,000 ~ 10,000		
CS3225	CC1210	1,000 ~ 3,000	4,000 ~ 10,000		
CS4520	CC1808	1,500 ~ 3,000	_		
CS4532	CC1812	500 ~ 1,000	1,500 ~ 5,000		

(5) Tape Dimensions



TYPE	EIA CODE	А	В	С	D	Е	F	G	Н	J
CS0603	CC0201	0.67±0.05	0.37±0.05	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
CS1005	CC0402	1.15±0.1	0.65±0.1	8.0±0.3	3.5±0.05	1.75±0.1	2.0±0.05	2.0±0.1	4.0±0.1	1.5±0.1
CS1608	CC0603	1.9±0.2	1.10±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS2012	CC0805	2.4±0.2	1.65±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS3216	CC1206	3.6±0.2	2.00±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS3225	CC1210	3.6±0.2	2.80±0.2	8.0±0.3	3.5±0.05	1.75±0.1	4.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS4520	CC1808	4.8±0.2	2.3±0.2	12.0±0.3	5.5±0.1	1.75±0.1	4.0±0.1 8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1
CS4532	CC1812	4.9±0.2	3.6±0.2	12.0±0.3	5.5±0.1	1.75±0.1	8.0±0.1	2.0±0.1	4.0±0.1	1.5±0.1



6.Caution

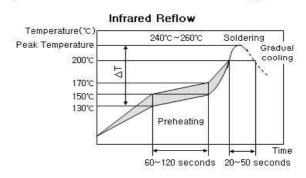
► Reflow Soldering

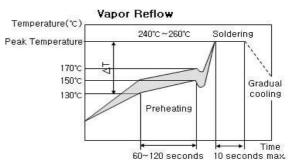
- 1. The sudden temperature change easily causes mechanical damages to ceramic components. Therefore, the preheating procedures should be required for the soldering of ceramic components.
- 2. Please refer to the recommended soldering profiles as shown in figures, and keep the temperature difference $(\triangle T)$ within the range recommended in Table 1.

Table 1

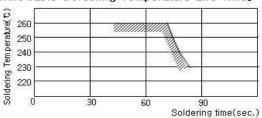
Size code	Temperature Difference
0603, 1005, 1608, 2012, 3216	△T≤190°C
3225size and over	△T≤130°C

[Standard Conditions for Reflow Soldering]





[Allowable Soldering Temperature and Time]



In case of repeated soldering, the accumulated soldering time must be within the range shown above.

► Storage Condition

*When Solderability is considered, Capacitor are recommended to be used in 12 months

(1) Temperature: 25° C ± 10° C

(2) Relative Humidity: Below 70% RH

▶ The Regulation of Environmental Pollution Materials.

*Never use materials mentioned below in MLCC products regulated this document.

Pb, Cd, Hg, Cr⁺⁶, PBB(Polybromide biphenyl), PBDE(Polybrominated diphenyl ethers), asbestos.

* Note

(1) 'Aging'/'De-aging' Behavior of high dielectric MLCCs

(Typically represented by X7R, Y5V temperature characteristic of which main composition is BaTiO3)

'Aging' / 'De-aging' Behavior of high dielectric MLCCs Please note that high dielectric type dielectric Ceramic Capacitors have a "normal" 'aging' behavior / characteristic, that is; their capacitance value decreases with time from its value when it was first manufactured. From that date, the capacitance value begins to decrease at a logarithmic rate defined by:

$$C_t = C_{24} (1 - k \log 10 t)$$

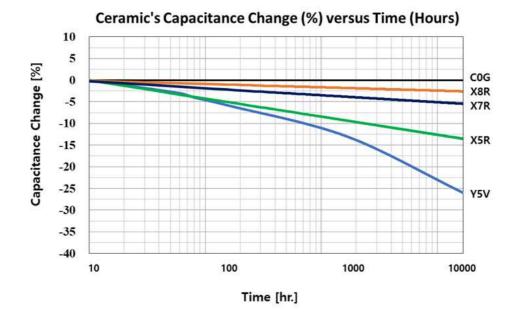
where:

Ct = Capacitance Value, t hours after the start of 'aging'

C₂₄ = Capacitance Value. 24 hours after its manufacture

k = aging constant (capacitance decrease per decade-hour)

t = time, in hours, from the start of 'aging'



The capacitance value can be restored (a.k.a. 'de-aged') by exposing the component to elevated temperatures approaching its Curie Temperature (approximately 120°C). This 'deaging' can occur during the component's solder-assembly onto the PCB, during life or temperature cycle testing., or by 'baking 'at 150°C for about 1 hour.

- (2) Please contact our sales representatives or product engineers before using the products in this catalog for the applications listed below, which require especially high reliability for the prevention of defects which might directly damage a third party's life, body or property, or when one of our products is intended for use in applications other than those specified in this catalog.
 - ①Aircraft equipment
- ②Aerospace equipment
- 3 Undersea equipment

- ©Transportation equipment (vehicles, trains, ships, etc.)
- Traffic signal equipment Spisaster prevention / crime prevention equipment